ASSOCIATION CONNECTING	■ Material Composit © Copyright 2005. IPC, international and Pan-Ar	Bannockb	urn, Illinois. A	ll rights reserved untions.	under both	This docum level parts, t	ent is a declara the declaration	tion of the sencompass	substances es all lowe	within the manufact or level materials for	urer listed which the	item. Note: if manufacturer	the item is an as has engineering	ssembly with lower responsibility.	
1752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute			*		Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information									
Supplier Informa	ation														
Company name* Compa				pany unique ID			Unique ID Authority				Respo	Response Date*			
onsemi											2025-0	5-05			
Contact Name 7			Title - Contac	Title - Contact			Phone - Contact*			Email	Email - Contact*				
Product-Env-Stewar	ds		Product Enviro Compliance				NA			Produ	Product-Env-Stewards@onsemi.com				
Authorized Representative* Tit			Title - Repres	Representative			Phone - Representative*			Email	Email - Representative*				
Product-Env-Stewards			Product Envi	iro Compliance NA Product-Env-Stewards@onser				rds@onsemi.co	m						
Requester Item Number Mfr Item		Mfr Item	Number Mfr Item Name			Effective Dat	e Versior	1]	Manufacturing Site		Weight*	UOM	Unit Type		
		E7111-0-	E7111-0-102A19-AG EZAIRO 7111, T&R		&R MPQ 250		2025-05-05			CA1		49.22926	mg	Each	
Manufacturing P	Proccess Information	n													
Terminal Plating / Grid Array Material Terminal Base			erminal Base A	Alloy	J-STD-020 MS	L Rating	Peak Pro	cess Body	Temperatu	re Max Time at Pea	k Temper	ature Numbe	er of Reflow Cy	cles	
SnAgCu CU Alloy 3			3		260		C	30	seco	onds 3					
Comments															
TTENTION: MSL	3 Rated item requires Ba	ake and D	ry Pack (after	electrical test)											
or more information	n regarding material con	position]	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		nium (Cr6+), Polybro	ominated Biphenyls (PBB), Polybron	dmium and quantity limit of 0.1% by mass (100 minated Diphenyl Ethers (PBDE), and Bis(2-eth	
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the
Supplier Digital Signature Ra	stislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Capacitor	3.39	mg	Supplier	Silicon Dioxide	7631-86-9		0.062	mg
			Supplier	Titanium Dioxide (TiO2)	13463-67-7		0.6855	mg
			Supplier	Boron Trioxide (B2O3)	1303-86-2		0.0155	mg
			Supplier	Tin (Sn)	7440-31-5		0.1915	mg
			Supplier	Misc.	Proprietary Data		0.2285	mg
			Supplier	Barium Monoxide (BaO)	1304-28-5		1.3711	mg
			В	Nickel (Ni)	7440-02-0		0.1381	mg
			Supplier	Copper (Cu)	7440-50-8		0.6978	mg
ie	10.50806	mg	Supplier	Silicon (Si)	7440-21-3		10.5081	mg
Laminate Board	15.05	mg	Supplier	triethylenediamine	280-57-9		0.0005	mg
			Supplier	Sodium citrate	68-04-2		0.0003	mg
			Supplier	Tetraammine palladium (II) dichloride	13815-17-3		0.0006	mg
			Supplier	D.I. Water	7732-18-5		0.0603	mg
			Supplier	Nickel Sulfamate	13770-89-3		0.1004	mg
			Supplier	copper	7440-66-6		5.2118	mg
			Supplier	copper foil	N/A		0.5659	mg
			Supplier	continuous filament fiber glass	N/A		1.7666	mg
			Supplier	Defoamers	N/A		0.078	mg
			Supplier	Phthalocyanine blue	N/A		0.0111	mg
			Supplier	Organic Filler	N/A		0.0134	mg
			Supplier	Acrylate resin	N/A		0.7846	mg
			Supplier	Diproplyeneglycolmonomethylether	34590-97-8		0.1672	mg
			Supplier	Gold Potassium Cyanide	13967-50-5		0.0067	mg
			Supplier	Thermosetting resin	Proprietary Data		3.7992	mg
			Supplier	Silica	Proprietary Data		0.0156	mg
			Supplier	Talc	14807-96-6		0.0468	mg
			Supplier	3-methoxy-3-methylbutylacetate	103429-90-9		0.3455	mg
			Supplier	Naphthalene	91-20-3		0.0156	mg
			Supplier	Fiber Glass (SiO2)	65997-17-3		0.297	mg
			Supplier	Photoinitiator	Proprietary Data		0.0802	mg
			Supplier	Palladium (Pd)	7440-05-3		0	mg
			В	Nickel (Ni)	7440-02-0		0	mg

			Supplier	Gold (Au)	7440-57-5	0	mg
			Supplier	Solvent Naphtha (Solvent oil)	64742-94-5	0.0802	mg
			Supplier	Copper (Cu)	7440-50-8	1.0117	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7	0.5907	mg
Mold Compound-Black	16.5	mg		Epoxy resin	proprietary data	1.32	mg
			Supplier	Phenol Resin	Proprietary Data	0.825	mg
			Supplier	Metal Hydroxide	Proprietary Data	0.165	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9	4.125	mg
			Supplier	Carbon Black (C)	1333-86-4	0.165	mg
			Supplier	Fused Silica (SiO2)	60676-86-0	9.9	mg
Solder Paste	3.12	mg	Supplier	2-(2-Hexyloxyethoxy) ethanol	112-59-4	0.1248	mg
			Supplier	Denatured Acid Hydrogenation Rosin	Proprietary	0.1248	mg
			Supplier	Dimer Acid	Proprietary	0.0624	mg
			Supplier	Silver (Ag)	7440-22-4	0.0936	mg
			Supplier	Tin (Sn)	7440-31-5	2.6832	mg
			Supplier	Copper (Cu)	7440-50-8	0.0312	mg
Wire Bond - Au	0.6612	mg	Supplier	Gold (Au)	7440-57-5	0.6612	mg